



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C241JB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 240pF, 50V, ±5%, C0G, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>241</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> <u>0</u>

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0603 (inch co	ode) L:	1.6	± 0.1	mm	W:	$0.8 \pm 0.1$	mm
				_				_	
3	Dielectric	C0G		8	Inner e	lectrode	N	li	
4	Capacitance	<b>240</b> pF			Termin	ation	C	u	
(5)	Capacitance	±5 %			<b>Plating</b>		S	n 100%	(Pb Free)
	tolerance			9	Produc	t	N	lormal	
6	Rated Voltage	50 V		10	Special		R	eserved for	future use
7	Thickness	$0.8 \pm 0.1$	mm	11)	Packag	ing	С	ardboard T	ype, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	1000 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characterisitcs	(From -55 $^{\circ}\!$						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating: 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within ±2.5% or ±0.25pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)				
Moisture	Capacitance change :	With rated voltage				
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q: 200 min					
	IR: 500Mohm or 25Mohm $\cdot \mu$ F					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature				
	Q: 350 min	1000+48/-0hrs				
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25°C				
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.